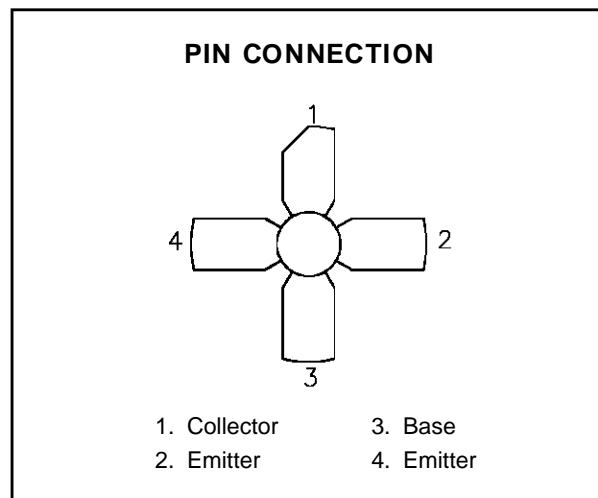
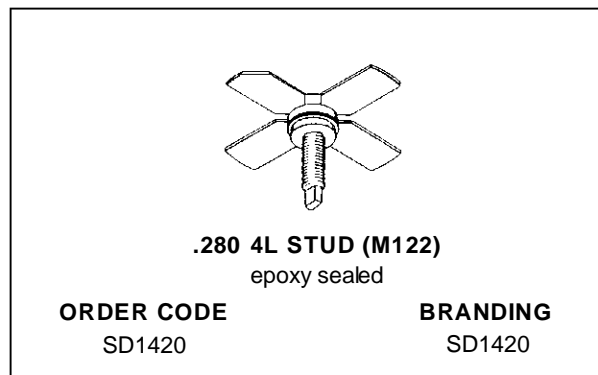


## RF & MICROWAVE TRANSISTORS 800-900 MHz BASE STATION APPLICATIONS

- 860 - 960 MHz
- 24 VOLTS
- COMMON EMITTER
- GOLD METALLIZATION
- CLASS A LINEAR OPERATION
- P<sub>OUT</sub> = 2.1 W MIN. WITH 9.0 dB GAIN


**DESCRIPTION**

The SD1420 is a gold metallized epitaxial silicon NPN planar transistor designed for high linearity Class A operation Cellular Base Station applications. The SD1420 is also available in a studless package as the SD1420-01.

**ABSOLUTE MAXIMUM RATINGS** (T<sub>case</sub> = 25°C)

Symbol	Parameter	Value	Unit
V <sub>CB0</sub>	Collector-Base Voltage	40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	28	V
V <sub>EBO</sub>	Emitter-Base Voltage	3.5	V
I <sub>C</sub>	Device Current	.250	A
P <sub>DISS</sub>	Power Dissipation	8.75	W
T <sub>J</sub>	Junction Temperature	+200	°C
T <sub>STG</sub>	Storage Temperature	- 55 to +150	°C

**THERMAL DATA**

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance	20	°C/W
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## SD1420

### ELECTRICAL SPECIFICATIONS ( $T_{\text{case}} = 25^{\circ}\text{C}$ )

#### STATIC

Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
$BV_{\text{CBO}}$	$I_{\text{C}} = 1 \text{ mA}$	$I_{\text{E}} = 0 \text{ mA}$	40	—	—	V
$BV_{\text{CEO}}$	$I_{\text{C}} = 1 \text{ mA}$	$I_{\text{B}} = 0 \text{ mA}$	28	—	—	V
$BV_{\text{EBO}}$	$I_{\text{E}} = 1 \text{ mA}$	$I_{\text{C}} = 0 \text{ mA}$	3.5	—	—	V
$I_{\text{CBO}}$	$V_{\text{CB}} = 24 \text{ V}$	$I_{\text{E}} = 0 \text{ mA}$	—	—	.5	mA
$h_{\text{FE}}$	$V_{\text{CE}} = 5 \text{ V}$	$I_{\text{C}} = 100 \text{ mA}$	20	—	120	—

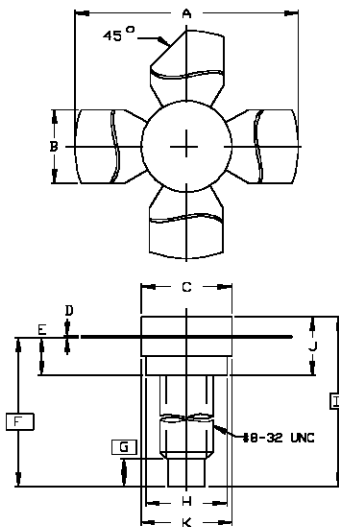
#### DYNAMIC

Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
$P_{\text{OUT}}$	$f = 960 \text{ MHz}$	$V_{\text{CE}} = 24 \text{ V}$	$I_{\text{CQ}} = 200 \text{ mA}$	2.1	—	—	W
$P_{\text{G}}$	$f = 960 \text{ MHz}$	$V_{\text{CE}} = 24 \text{ V}$	$I_{\text{CQ}} = 200 \text{ mA}$	8.9	9.0	—	dB
$C_{\text{OB}}$	$f = 1 \text{ MHz}$	$V_{\text{CB}} = 28 \text{ V}$		—	—	5	pF

Note: \* $P_{\text{IN}} = 0.27 \text{ W}$

## PACKAGE MECHANICAL DATA

Ref.: Dwg. No.12-0122 rev. B



SGS-THOMSON MICROELECTRONICS		
	MINIMUM Inches/mm	MAXIMUM Inches/mm
A	1.010/25,65	1.055/26,80
B	.220/5,59	.230/5,84
C	.270/6,86	.285/7,24
D	.003/0,08	.007/0,18
E	.117/2,97	.137/3,48
F	.572/14,53	
G	.130/3,30	
H	.245/6,22	.255/6,48
I	.640/16,26	
J	.175/4,45	.217/5,51
K	.275/6,99	.285/7,24

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